

Title (en)  
HEATING ELEMENT, FABRICATION PROCESS AND APPLICATION

Title (de)  
HEIZELEMENT, HERSTELLUNGSVERFAHREN UND ANWENDUNG

Title (fr)  
ELEMENT CHAUFFANT, PROCEDE DE FABRICATION ET APPLICATION

Publication  
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Application  
**EP 96910147 A 19960430**

Priority

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Abstract (en)  
[origin: US6054690A] PCT No. PCT/IB96/00390 Sec. 371 Date Feb. 19, 1998 Sec. 102(e) Date Feb. 19, 1998 PCT Filed Apr. 30, 1996 PCT Pub. No. WO96/35317 PCT Pub. Date Nov. 7, 1996A heating element includes at least one substrate, at least one electrical resistance layer, and a binder configured to bind the electrical resistance layer to the substrate, wherein the binder has a melting temperature greater than an operating temperature of the heating element and includes a perfluorinated polymer.

IPC 1-7  
**H05B 3/28**

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